

## **ABSTRACT**

A device and method for cleaning a wafer are provided. The device includes: a cleaning tank; a first pump for pumping an etching liquid at the bottom of the cleaning tank to a liquid surface of the etching liquid in the cleaning tank via outside the cleaning tank in a process of immersing the wafer into the etching liquid, so that the etching liquid in the cleaning tank moves downward to remain stationary relative to the wafer; and a second pump for pumping the etching liquid at the liquid surface to the bottom of the cleaning tank via outside the cleaning tank in a process of moving the wafer out of the etching liquid, wherein the etching liquid in the cleaning tank moves upward to remain stationary relative to the wafer.

(Figure 1)